

TITLE OF THE INVENTION: ELECTRONIC PACKAGE ASSEMBLY WITH A COOLING SYSTEM AND A METHOD FOR FORMING THE SAME

Abstract

An electronic package assembly and a method for forming the same are provided. The electronic package assembly comprises: a base package substrate, at least one base electronic component, and a base mold cap; a support frame attached on the base mold cap, wherein the support frame has a base opening exposing the base mold cap and the front surface of the base electronic component, and an upper opening in fluid communication with the base opening; an upper package substrate supported on the support frame, at least one upper electronic component facing towards the base electronic component, and an upper mold cap accommodated within the support frame, and the upper mold cap has a height smaller than that of the support frame to form a cooling passage between the upper mold cap and the base mold cap; and wherein the upper package substrate comprises an inlet and an outlet formed therethrough.

(Fig. 1A)